

# POWER MOS FET FIELD EFFECT POWER TRANSISTOR

### VN46AFA Series

1.2 AMPERES 40-80 VOLTS RDS(ON) = 3.0, 4.0 Ω

This series of N-Channel Enhancement-mode Power MOSFETs utilizes GE's advanced Power DMOS technology to achieve low on-resistance with excellent device ruggedness and reliability.

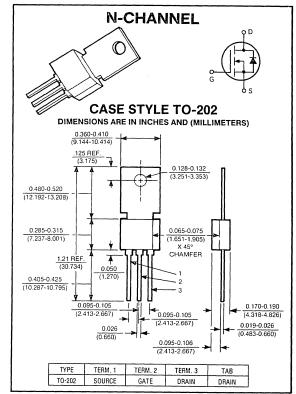
This design has been optimized to give superior performance in most switching applications including: switching power supplies, inverters, converters and solenoid/relay drivers. Also, the extended safe operating area with good linear transfer characteristics makes it well suited for many linear applications such as audio amplifiers and servo motors.

#### **Applications**

- Switching power supplies
- DC to DC inverters
- CMOS and TTL to high current interface
- Line drivers
- Logic buffers
- Pulse amplifiers

#### **Features**

- · High speed, high current switching
- Current sharing capability when paralleled
- Directly interface to CMOS, DTL, TTL logic
- Simple DC biasing
- Extended safe operating area
- Inherently temperature stable



#### maximum ratings (T<sub>A</sub> = 25°C) (unless otherwise specified)

RATING	SYMBOL	VN46AFA	VN66AFA	VN88AFA	UNITS
Drain-Source Voltage	V <sub>DSS</sub>	40	60	80	Volts
Drain-Gate Voltage, $R_{GS} = 1M\Omega$	V <sub>DGR</sub>	40	60	80	Volts
Continuous Drain Current @ T <sub>A</sub> = 25° C	ID	1.2	1.2	1.2	А
Peak Drain Current	I <sub>DM</sub>	3.0	3.0	3.0	Α
Gate-Source Voltage	V <sub>GS</sub>	±30	±30	±30	Volts
Total Power Dissipation @ T <sub>A</sub> = 25°C Derate Above 25°C	P <sub>D</sub>	12 96	12 96	12 96	Watts mW/°C
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-40 to 150	-40 to 150	-40 to 150	°C

#### thermal characteristics

Thermal Resistance, Junction to Ambient	$R_{ heta JA}$	10.4	10.4	10.4	°C/W
Maximum Lead Temperature for Soldering Purposes: 1/6" from Case for 5 Seconds	TL	300	300	300	°C

# electrical characteristics ( $T_A = 25^{\circ}C$ ) (unless otherwise specified)

f = 1 MHz

CHARACTERISTIC		SYMBOL	MIN	TYP	MAX	UNIT
off characteristics						
Drain-Source Breakdown Voltage $(V_{GS} = 0V, I_D = 10 \mu A)$	VN46AFA VN66AFA VN88AFA	BVDSS	40 60 80	=		Volts
Zero Gate Voltage Drain Current (V <sub>DS</sub> = Max Rating, V <sub>GS</sub> = 0V) (V <sub>GS</sub> = Max Rating, × 0.8, V <sub>GS</sub> = 0V	, T <sub>A</sub> = 125°C)	IDSS	_	_	10 100	μΑ
Gate-Source Leakage Current (V <sub>GS</sub> = 10V, V <sub>DS</sub> = 0V) (V <sub>GS</sub> = 10V, V <sub>DS</sub> = 0V - T <sub>A</sub> = 125 °C	S)	IGSS		0.01	10 100	μΑ
on characteristics						
Gate Threshold Voltage (V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 1 mA)		V <sub>GS(TH)</sub>	0.8	1.7		Volts
Drain-Source Saturation Voltage (V <sub>GS</sub> = 10V, I <sub>D</sub> = 1.0A)	VN40AFA;VN66AFA VN88AFA	V <sub>DS(ON)</sub>	_	=	3.0 4.0	Α
Static Drain-Source On-State Resista (V <sub>GS</sub> = 10V, I <sub>D</sub> = 1.0A)	ince	R <sub>DS(ON)</sub>	_	=	3.0 4.0	Ohms
Forward Transconductance (V <sub>DS</sub> = 24V, I <sub>D</sub> = 0.5A, f = 1 KHz)		9fs ·	.150	.25	_	mhos
dynamic characteristics						
Input Capacitance V	'GS = 0V	C <sub>iss</sub>			50	pF
Output Capacitance V	<sub>DS</sub> = 25V	Coss			50	pF

## switching characteristics

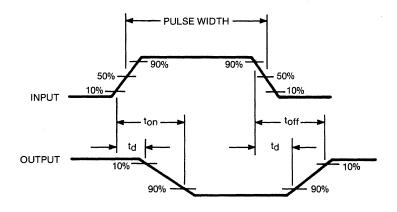
Reverse Transfer Capacitance

Turn-on Delay Time	See switching times	t <sub>d(on)</sub>	_	2	5	ns
Rise Time	waveform below	T <sub>r</sub>	_	2	5	ns
Turn-off Delay Time		t <sub>d(off)</sub>	_	2	5	ns
Fall Time		t <sub>f</sub>	_	2	5	ns

Crss

10

pF



**SWITCHING TIME TEST WAVEFORMS**